

ONE STEP COPPER DAMASCENE CMP PROCESS AND SLURRY THEREFORE

ABSTRACT

A Chemical Mechanical Polish (CMP) process and slurry therefore slurry that is capable of removing NiFe, SiO₂, Photoresist, Ta, alumina and Cu at substantially the same rate. The slurry is useful for obtaining a substantially planar surface of several materials while avoiding corrosion of Cu coil and NiFe structure.